

# 74ABT125

## Quad Buffer with 3-STATE Outputs

### Features

- Non-inverting buffers
- Output sink capability of 64mA, source capability of 32mA
- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability
- Disable time less than enable time to avoid bus contention

### General Description

The ABT125 contains four independent non-inverting buffers with 3-STATE outputs.

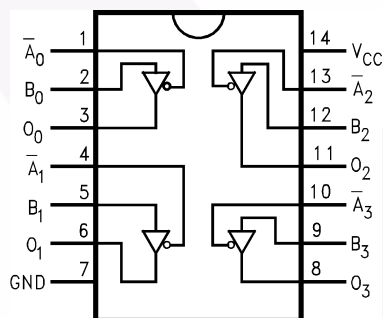
### Ordering Information

| Order Number | Package Number | Package Description                                                          |
|--------------|----------------|------------------------------------------------------------------------------|
| 74ABT125CSC  | M14A           | 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| 74ABT125CSJ  | M14D           | 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide                |
| 74ABT125CMT  | MTC14          | 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide  |

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

 All packages are lead free per JEDEC: J-STD-020B standard.

### Connection Diagram



### Function Table

| Inputs         |                | Output         |
|----------------|----------------|----------------|
| A <sub>n</sub> | B <sub>n</sub> | O <sub>n</sub> |
| L              | L              | L              |
| L              | H              | H              |
| H              | X              | Z              |

H = HIGH Voltage Level

L = LOW Voltage Level

Z = HIGH Impedance

X = Immaterial

### Pin Description

| Pin Names                       | Description |
|---------------------------------|-------------|
| A <sub>n</sub> , B <sub>n</sub> | Inputs      |
| O <sub>n</sub>                  | Outputs     |

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol    | Parameter                                                                  | Rating                             |
|-----------|----------------------------------------------------------------------------|------------------------------------|
| $T_{STG}$ | Storage Temperature                                                        | –65°C to +150°C                    |
| $T_A$     | Ambient Temperature Under Bias                                             | –55°C to +125°C                    |
| $T_J$     | Junction Temperature Under Bias                                            | –55°C to +150°C                    |
| $V_{CC}$  | $V_{CC}$ Pin Potential to Ground Pin                                       | –0.5V to +7.0V                     |
| $V_{IN}$  | Input Voltage <sup>(1)</sup>                                               | –0.5V to +7.0V                     |
| $I_{IN}$  | Input Current <sup>(1)</sup>                                               | –30mA to +5.0mA                    |
| $V_O$     | Voltage Applied to Any Output<br>Disabled or Power-Off State<br>HIGH State | –0.5V to 5.5V<br>–0.5V to $V_{CC}$ |
|           | Current Applied to Output in LOW State (Max.)                              | twice the rated $I_{OL}$ (mA)      |
|           | DC Latchup Source Current (Across Comm Operating Range)                    | –300mA                             |
|           | Over Voltage Latchup (I/O)                                                 | 10V                                |

### Note:

1. Either voltage limit or current limit is sufficient to protect inputs.

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol                | Parameter                    | Rating         |
|-----------------------|------------------------------|----------------|
| $T_A$                 | Free Air Ambient Temperature | –40°C to +85°C |
| $V_{CC}$              | Supply Voltage               | +4.5V to +5.5V |
| $\Delta V / \Delta t$ | Minimum Input Edge Rate      |                |
|                       | Data Input                   | 50mV/ns        |
|                       | Enable Input                 | 20mV/ns        |

## DC Electrical Characteristics

| Symbol           | Parameter                                      |                 | V <sub>CC</sub> | Conditions                                                                                  | Min. | Typ. | Max. | Units  |
|------------------|------------------------------------------------|-----------------|-----------------|---------------------------------------------------------------------------------------------|------|------|------|--------|
| V <sub>IH</sub>  | Input HIGH Voltage                             |                 |                 | Recognized HIGH Signal                                                                      | 2.0  |      |      | V      |
| V <sub>IL</sub>  | Input LOW Voltage                              |                 |                 | Recognized LOW Signal                                                                       |      |      | 0.8  | V      |
| V <sub>CD</sub>  | Input Clamp Diode Voltage                      |                 | Min.            | I <sub>IN</sub> = -18mA                                                                     |      |      | -1.2 | V      |
| V <sub>OH</sub>  | Output HIGH Voltage                            |                 | Min.            | I <sub>OH</sub> = -3mA                                                                      | 2.5  |      |      | V      |
|                  |                                                |                 |                 | I <sub>OH</sub> = -32mA                                                                     | 2.0  |      |      |        |
| V <sub>OL</sub>  | Output LOW Voltage                             |                 | Min.            | I <sub>OL</sub> = 64mA                                                                      |      |      | 0.55 | V      |
| I <sub>IH</sub>  | Input HIGH Current                             |                 | Max.            | V <sub>IN</sub> = 2.7V <sup>(2)</sup>                                                       |      |      | 1    | μA     |
|                  |                                                |                 |                 | V <sub>IN</sub> = V <sub>CC</sub>                                                           |      |      | 1    |        |
| I <sub>BVI</sub> | Input HIGH Current Breakdown Test              |                 | Max.            | V <sub>IN</sub> = 7.0V                                                                      |      |      | 7    | μA     |
| I <sub>IL</sub>  | Input LOW Current                              |                 | Max.            | V <sub>IN</sub> = 0.5V <sup>(2)</sup>                                                       |      |      | -1   | μA     |
|                  |                                                |                 |                 | V <sub>IN</sub> = 0.0V                                                                      |      |      | -1   |        |
| V <sub>ID</sub>  | Input Leakage Test                             |                 | 0.0             | I <sub>ID</sub> = 1.9μA, All Other Pins Grounded                                            | 4.75 |      |      | V      |
| I <sub>OZH</sub> | Output Leakage Current                         |                 | 0-5.5V          | V <sub>OUT</sub> = 2.7V, $\overline{OE}_n$ = 2.0V                                           |      |      | 10   | μA     |
| I <sub>OZL</sub> | Output Leakage Current                         |                 | 0-5.5V          | V <sub>OUT</sub> = 0.5V, $\overline{OE}_n$ = 2.0V                                           |      |      | -10  | μA     |
| I <sub>OS</sub>  | Output Short-Circuit Current                   |                 | Max.            | V <sub>OUT</sub> = 0.0V                                                                     |      |      | -275 | mA     |
| I <sub>CEX</sub> | Output HIGH Leakage Current                    |                 | Max.            | V <sub>OUT</sub> = V <sub>CC</sub>                                                          |      |      | 50   | μA     |
| I <sub>ZZ</sub>  | Bus Drainage Test                              |                 | 0.0             | V <sub>OUT</sub> = 5.5V, All Others GND                                                     |      |      | 100  | μA     |
| I <sub>CCH</sub> | Power Supply Current                           |                 | Max.            | All Outputs HIGH                                                                            |      |      | 50   | μA     |
| I <sub>CCL</sub> | Power Supply Current                           |                 | Max.            | All Outputs LOW                                                                             |      |      | 15   | mA     |
| I <sub>CCZ</sub> | Power Supply Current                           |                 | Max.            | $\overline{OE}_n$ = V <sub>CC</sub> , All Others at V <sub>CC</sub> or Ground               |      |      | 50   | μA     |
| I <sub>CCT</sub> | Additional I <sub>CC</sub> /Input              | Outputs Enabled | Max.            | V <sub>I</sub> = V <sub>CC</sub> - 2.1V                                                     |      |      | 1.5  | mA     |
|                  |                                                | Outputs 3-STATE |                 | Enable Input V <sub>I</sub> = V <sub>CC</sub> - 2.1V                                        |      |      | 1.5  | mA     |
|                  |                                                | Outputs 3-STATE |                 | Data Input V <sub>I</sub> = V <sub>CC</sub> - 2.1V, All Others at V <sub>CC</sub> or Ground |      |      | 50   | μA     |
| I <sub>CCD</sub> | Dynamic I <sub>CC</sub> No Load <sup>(2)</sup> |                 | Max.            | Outputs OPEN, $\overline{OE}_n$ = GND <sup>(3)</sup> , One-Bit Toggling, 50% Duty Cycle     |      |      | 0.1  | mA/MHz |

## Notes:

2. Guaranteed, but not tested.
3. For 8-bit toggling, I<sub>CCD</sub> < 0.8mA/MHz.

**AC Electrical Characteristics**

| Symbol    | Parameter                          | $T_A = +25^{\circ}\text{C}$ ,<br>$V_{CC} = +5\text{V}$ ,<br>$C_L = 50\text{pF}$ |      |      | $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$<br>$V_{CC} = 4.5\text{V} - 5.5\text{V}$<br>$C_L = 50\text{pF}$ |      | Units |
|-----------|------------------------------------|---------------------------------------------------------------------------------|------|------|--------------------------------------------------------------------------------------------------------------------|------|-------|
|           |                                    | Min.                                                                            | Typ. | Max. | Min.                                                                                                               | Max. |       |
| $t_{PLH}$ | Propagation Delay, Data to Outputs | 1.0                                                                             |      | 4.6  | 1.0                                                                                                                | 4.6  | ns    |
| $t_{PHL}$ |                                    | 1.0                                                                             |      | 4.9  | 1.0                                                                                                                | 4.9  |       |
| $t_{PZH}$ | Output Enable Time                 | 1.0                                                                             |      | 5.1  | 1.0                                                                                                                | 5.1  | ns    |
| $t_{PZL}$ |                                    | 1.0                                                                             |      | 6.8  | 1.0                                                                                                                | 6.8  |       |
| $t_{PHZ}$ | Output Disable Time                | 1.0                                                                             |      | 6.2  | 1.0                                                                                                                | 6.2  | ns    |
| $t_{PLZ}$ |                                    | 1.0                                                                             |      | 5.5  | 1.0                                                                                                                | 5.5  |       |

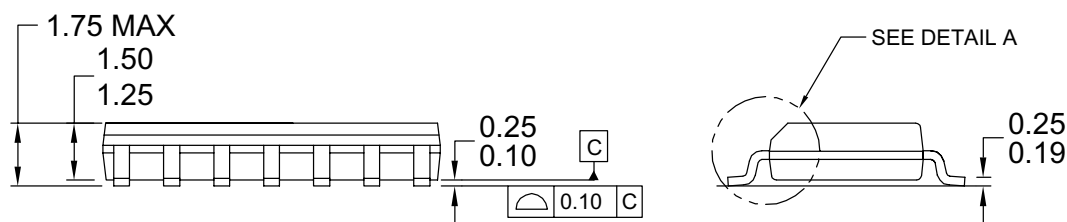
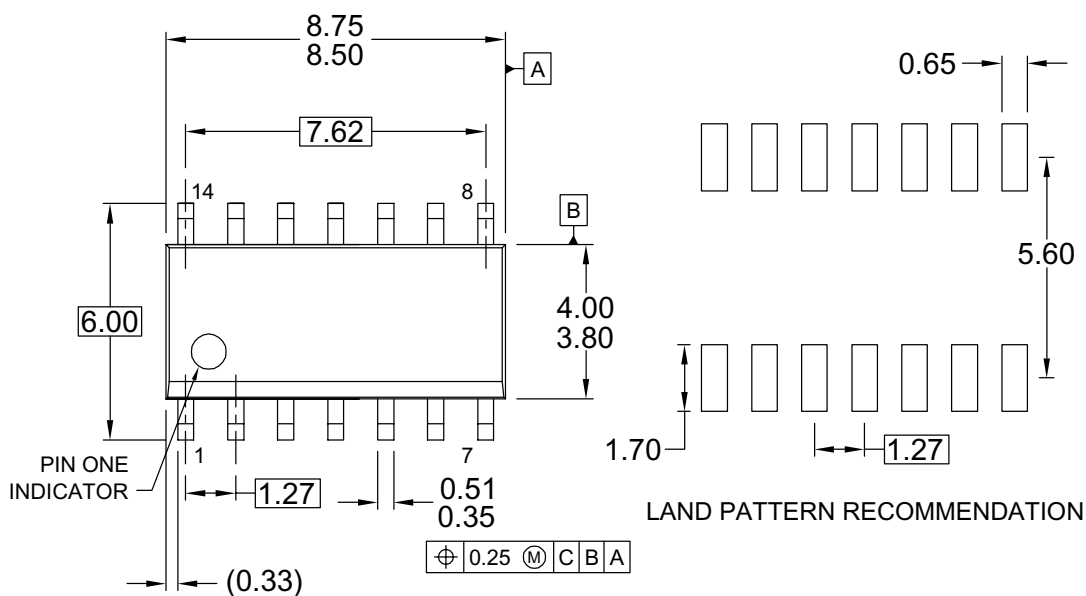
**Capacitance**

| Symbol          | Parameter          | Conditions<br>$T_A = 25^{\circ}\text{C}$ | Typ. | Units |
|-----------------|--------------------|------------------------------------------|------|-------|
| $C_{IN}$        | Input Capacitance  | $V_{CC} = 0\text{V}$                     | 5.0  | pF    |
| $C_{OUT}^{(4)}$ | Output Capacitance | $V_{CC} = 5.0\text{V}$                   | 9.0  | pF    |

**Note:**

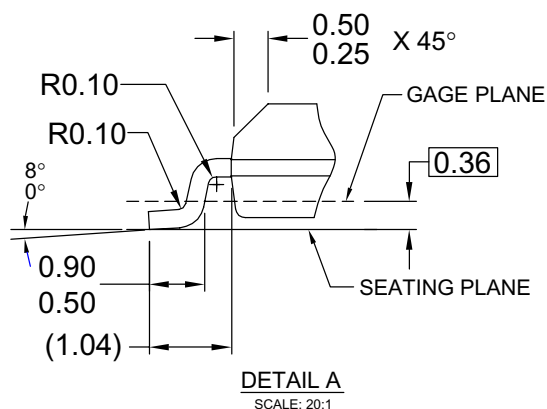
4.  $C_{OUT}$  is measured at frequency  $f = 1\text{MHz}$ , per MIL-STD-883, Method 3012.

## Physical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD:  
SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13



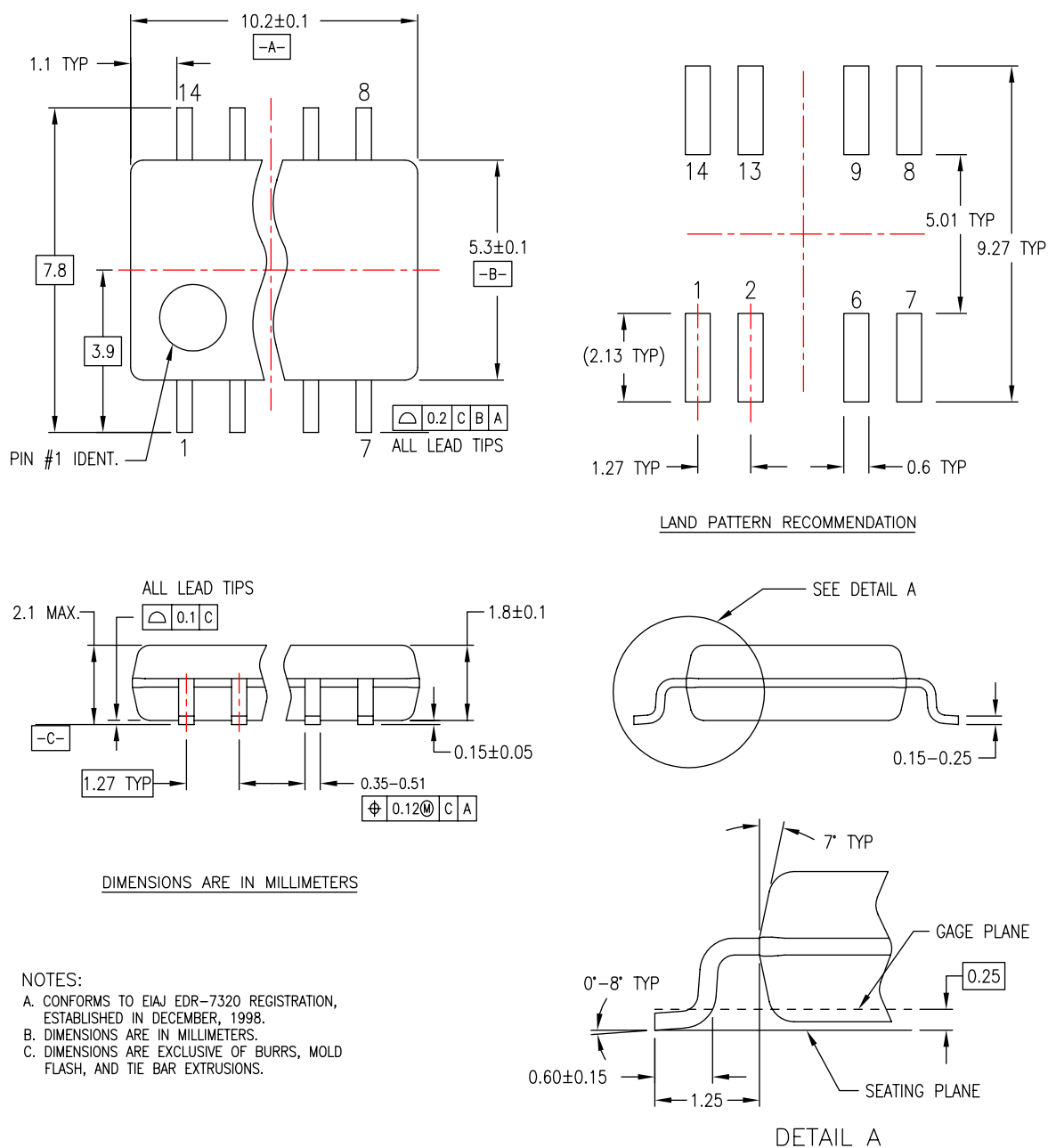
**Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow**

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## Physical Dimensions (Continued)



M14DREVC

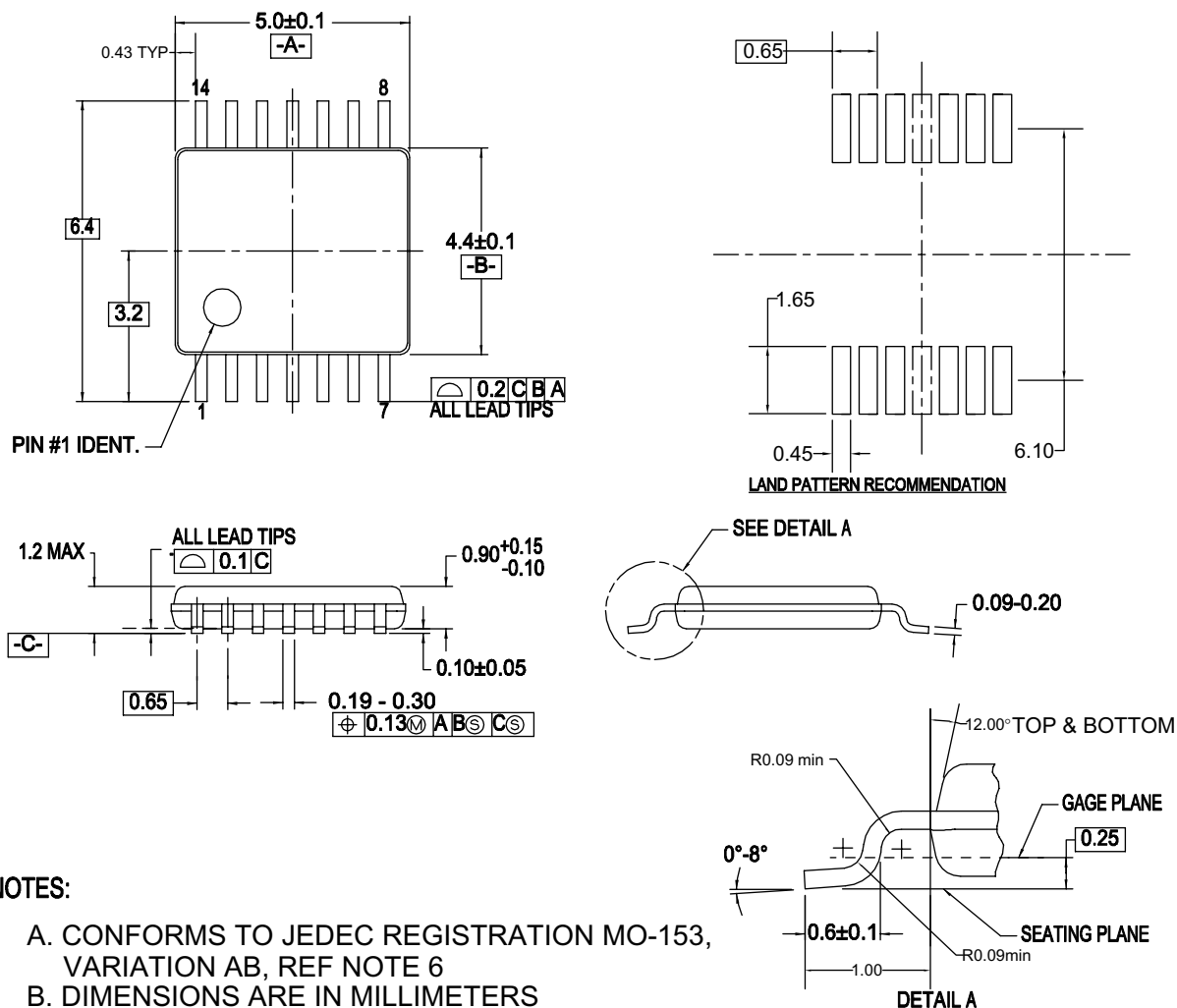
Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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## Physical Dimensions (Continued)



## NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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|                                                                                     |                        | SuperSOT™-6                |                      |
|                                                                                     |                        | SuperSOT™-8                |                      |

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Rev. I32



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